

Product Data Sheet

ATCA Power,
Part No. 511-50500-193

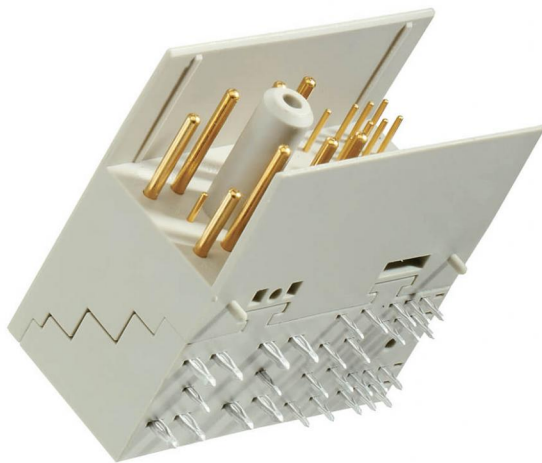


Illustration similar



Perpendicular



Press-fit



Power



Rugged

- contacts: 22 signal, 8 power
- Press-fit
- according to PICMG specifications



» to product on www.ept.de



» to product group Advanced TCA

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Technical Specifications

Basics

Specification	PICMG® 3.0 R2.0
No. of Contacts	30 (8 Power, 22 Signal)
Termination Technology	Press-fit
Termination Length	4.1 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	PBT glass filled, UL 94 V-0
Contact Material	Copper alloy
Plating	Au over Ni

Mechanical

Mating Force	max. 67 N
Separating Force	max. 67 N
Durability	250 mating cycles

Electrical

Operational Current	Power contacts: max. 16 A, Signal contacts: max. 1 A
Insulation Resistance	$\geq 10^{10} \Omega$
Test Voltage	Contact 1 - 16: 1000 V r.m.s; contact 17 - 34: 2000 V r.m.s.

Approval / Compliance

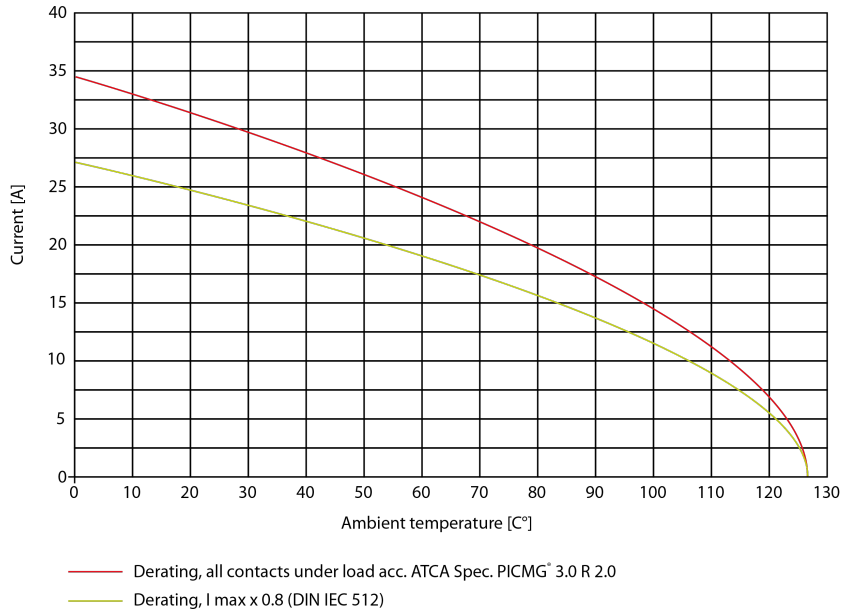
UL file	E130314
Environment	RoHS compliant

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Derating Diagram



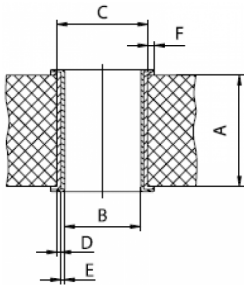
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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	imm. Sn printed circuit boards
Nominal Hole	Ø 1.0 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	imm. Sn plating, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au printed circuit boards
Nominal Hole	Ø 1.0 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Material	imm. Sn printed circuit boards
Nominal Hole	Ø 1.6 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.6 +0.09 / -0.06 mm
C Drill Hole	1.75 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	imm. Sn plating, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au printed circuit boards
Nominal Hole	Ø 1.6 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.6 +0.09 / -0.06 mm
C Drill Hole	1.75 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

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Modifications

Available on request

- different number of contacts

Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)

[» 3D IGES](#)

[» 3D STEP](#)

[» 3D PDF](#)